

RoHS **Compliant** 



### **Features**

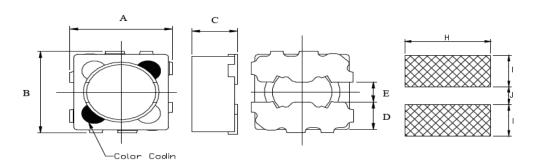
- Low profile, low RDC, lower resistance and high current handling capacities
- Flat bottom surface ensures secure, reliable mounting
- Magnetically shielded structure that ensures the high-density mounting configurations

## **Applications**

- · PDA, DSC, PDA And Other Electronic Equipments
- Hard Disk Drives
- Low Profile/ Low Resistance Specifically Suitable For Portable Telephones

### **Characteristics**

- Saturation Rated Current(IDC): The current when the inductance becomes 10% or 35% lower than its initial value.
- Temperature Rise Current (Irms): For a 25°C rise above 25°C ambient.
- Operating temperature range: -25°C to 105°C



**Dimensions** Unit: mm

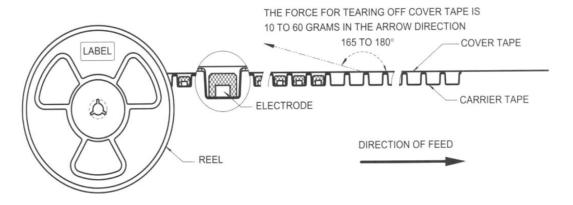
Code	Α	В	C max.	D	E	н	I	J
10	3.2±0.2	3.2±0.2	1.05	1.1	0.8	3.6	1.4	0.8
18	4.2±0.2	4.2±0.2	1.8	1.3	1.4	4.6	1.6	1.4

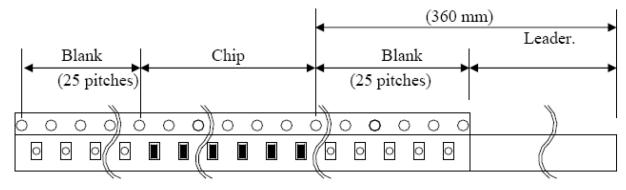
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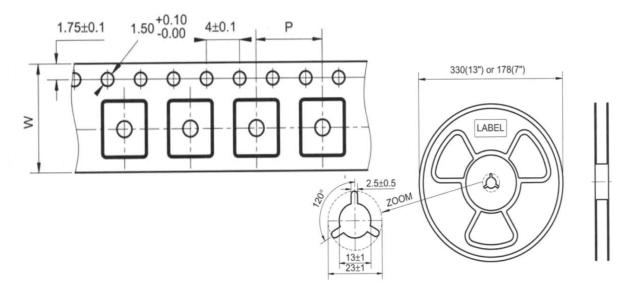




# Tape and Reel specifications









Unit: mm

Casa Cada	Таре	Parts Per Reel		
Case Code	W	Р	7"	
10	40	0	1000	
18	12	0		

# **SMT Power Inductor Environmental Specifications**

## General

Items	Specifications				
Shelf Storage conditions	Temperature range: 15°C to 28°C; Humidity: <80% relative humidity. Recommended product should be used within one year from the time of delivery.				

### **Environmental test**

Test Items	Specifications	Test Conditions / Test Methods		
High temperature Storage test		Temperature 85±2°C, Time: 48±2 hours, Tested after 1 hour at room temperature.		
Low temperature Storage test	No case deformation or change in appearance. ΔL/L≤10%	Temperature -25±2°C, Time: 48±2 hours, Tested after 1 hour at room temperature.		
Humidity test		Temperature 40±2°C, 90% to 95% relative humidity Time: 96±2 hours Tested after 1 hour at room temperature.		
Thermal shock test		First -25°C 30 minutes then 25°C 10 minutes last 85°C 30 minutes, as 1 cycle. Go through 5 cycles. Tested after 1 hour at room temperature.		

## **Mechanical test**

Test Items	Specifications	Test Conditions / Test Methods			
Solderability test	Terminal area must have 90% minimum solder coverage.	Product with Lead-free terminal: Dip pads in flux then dip in solder pot at 245±5°C for 3 seconds.			
Resistance to Soldering Heat	No case deformation or change in appearance.	Flux should cover the whole of the sample before heating, then be preheated for about 2 minutes over temperature of 130°C to 150°C. Immersing to 260±5°C for 10 seconds.			
Vibration test	No case deformation or change in	Apply frequency 10Hz to 55Hz. 1.5mm amplitude in each of perpendicular direction for 2 hours.			
Shock resistance	appearance. ΔL/L≤10%	Drop down with 981m/s² (100G) shock attitude upon a rubber block method shock testing machine, for 1 time. In each of three orientations.			

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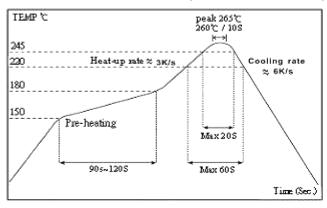




### **Electrical Characteristics**

Part No	Code L (µH)		Tolerance	Test Condition	DCR (Ω) max.	IDC (A) Typ.		I rms	Colour Code
		(μπ)				L drop 10%	L drop 35%	(A) Typ.	
MP002871	10	6.8	20%	1kHz, 1V	0.33	0.46	0.6	0.7	White
MP002872	18	10			0.165	0.9	1.1	1.05	Red

## The condition of reflow (recommendation)



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